

1 2 3 4 5 6

The Stackup Legend below this is static.
If you change the stackup, update the Legend.

Layer Name	Order	Copper Thickness	Dielectric Material
Top Solder Mask	C.0TS		Solder Resist
Top Layer	C.0TL	1.4mil	FR-4
Bottom Layer	C.0BL	1.4mil	FR-4
Bottom Solder Mask	C.0BS		Solder Resist

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
3450MIL X 4950MIL

Number of Layers : 2
 MIN. TRACK WIDTH: 8 MIL
 MIN. CLEARANCE: 8 MIL
 MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
 PER IPC-D-275 CLASS 2 LEVEL C
 REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:

FR-408 FR-4 High Tg OTHER _____
 THICKNESS: 62 MIL (1.6mm) +/-10% OTHER _____
 TOLERANCE: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____
 BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

COPPER THICKNESS (FINISHED):

OUTER: 1.4MIL (1oz) 2MIL (1.4oz) 2.8MIL (2oz)
 INNER SIGNAL: 1.4MIL (1oz) 2.8MIL (2oz) N/A

DRILLING:

REFERENCE: AS SHOWN NC_DRILL FILES
 PTH MIN COPPER THICKNESS: 1MIL OTHER _____

BOARD FINISH:

SILKSCREEN: TOP BOTTOM
 SILKSCREEN COLOR: WHITE OTHER _____
 SOLDER RESIST COLOR:
 GREEN BLUE OTHER _____

SURFACE FINISH:

IMMERSION GOLD (ENIG) ENERP
 IMM. TIN/SILVER OR EQUIV OTHER _____

ARRAY/PANEL:

CUT AND TRIM PER MECH LAYER 1
 N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:

ANSI IPC-A-600F CLASS -> 1 2 3
 UL 94V-0 RoHS OTHER PER ORDER

ADDITIONAL REQUIREMENTS:

MICROSECTION: YES
 BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER
 MANUFACTURER'S UL: RAIL METAL SILK



PROJECT TITLE:
UCC28910 5U 5H

DESIGNED FOR:
Public Release

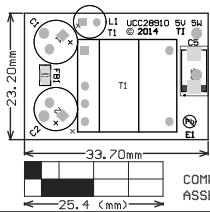
FILE NAME:
5UPS_PcbDoc

ENGINEER:
Mars Leung

LAYOUT BY:
Mars Leung

SCALE: 0,72

ALTIUM DESIGNER VERSION:
14.3.18.45973



TIDC-4FI-METER-READING

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COMPONENTS MARKED 'DNP' SHOULD NOT BE ORDERED OR SHOWN IN THE BOM
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 ASSEMBLY VARIANT: [No Variations] ASSEMBLY VARIANT: [No Variations]

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1 2 3 4 5 6

A

B

C

D

A

B

C

D

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Top Layer	(G,TL)		1.4mil	FR-4
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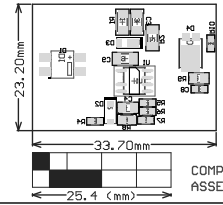
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Mars Leung

LAYOUT BY:
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14,3,18,45973



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ADDITIONAL COMMENTS	DATE	BY	DESCRIPTION
	10/26/2013		GENERATED

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